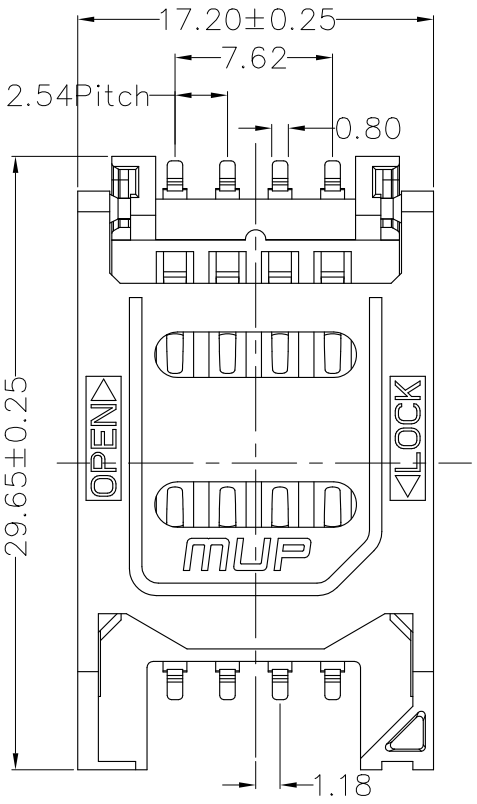
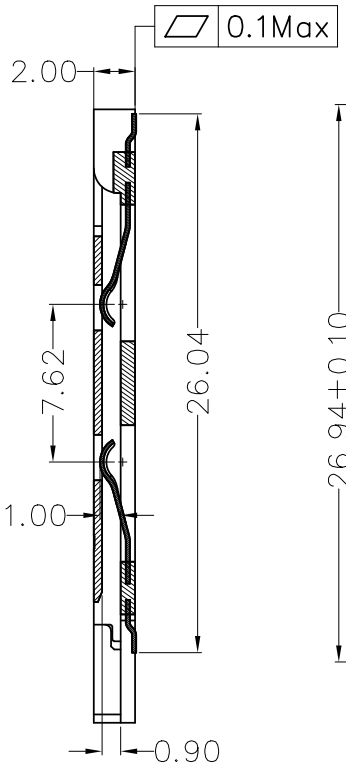
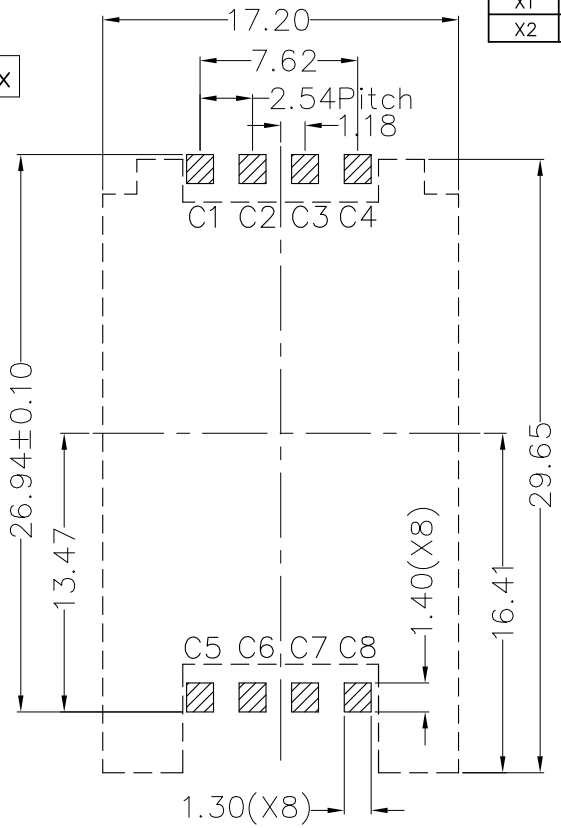
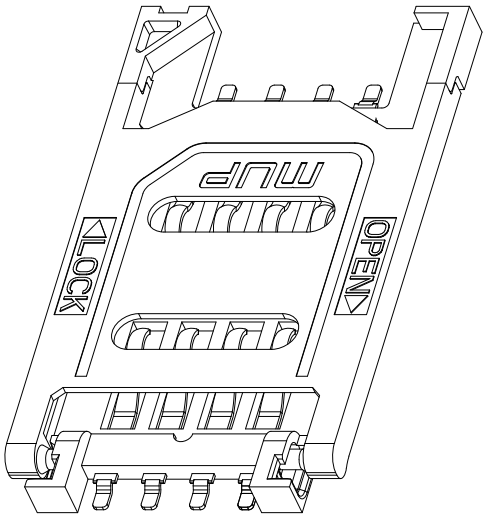
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					

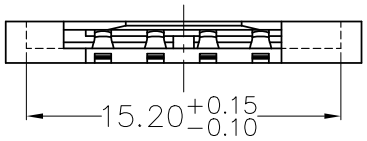






RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)





TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 29.65LX17.20WX2.00H mm

Weight: Approx 0.76±0.2g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max

IR reflow: 250°C,5sec.Max

Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: −40°C~+85°C

Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi−temp Thermoplastic	Black UL94V−0
2	COVER	1	Hi−temp Thermoplastic	Black UL94V−0
3	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X°	±5°
X.X	±0.25	X.X°	±4°
X.XX	±0.15	X.XX°	±3°
X.XXX	±0.10	X.XXX°	±2°

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C710-3**

TYPE : **H2.0 without post 8p**

PROJ.	UNIT	SCALE
	mm	1:1

CUSTOMER DRAWING

DRAWN	Zoey	Nov.14.2007
CHECKED	Jimmy	Nov.14.2007
APPROVAL	Simon	Nov.14.2007

DWG NO.: DWG−MUP−C710−003

SHEET 1/1

REVISION X1

Pb RoHS PROCESS COMPLIANT